# imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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### Contact us

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### MOS FET FK3506010L

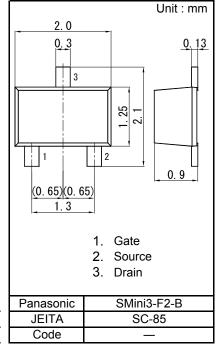
FK3506010L Silicon N-channel MOS FET

For switching

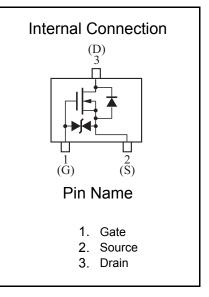
FK330601 in SMini3 type package

- Features
- Low drive voltage : 2.5 V drive
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol : CV
- Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C							
Parameter	Symbol	Rating	Unit				
Drain-source voltage	VDS	60	V				
Gate-source voltage	VGS	±12	V				
Drain current	ID	100	mA				
Pulse drain current	IDp	200	mA				
Total power dissipation	PD	150	mW				
Channel temperature	Tch	150	°C				
Operating ambient temperature	Topr	-40 to +85	°C				
Storage temperature	Tstg	-55 to +150	°C				

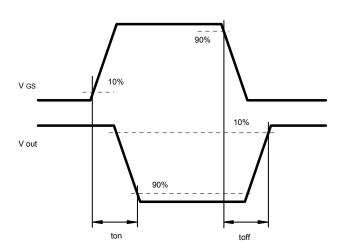


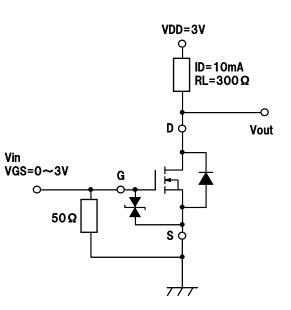
## **Panasonic**

### MOS FET FK3506010L

■ Electrical Characteristics Ta = 25 °C ± 3 °C								
Parameter	Symbol	Conditions	Min	Тур	Max	Unit		
Drain-source breakdown voltage	VDSS	ID = 1 mA, VGS = 0	60			V		
Drain-source cutoff current	IDSS	VDS = 60 V, VGS = 0			1.0	μA		
Gate-source cutoff current	IGSS	VGS = ±10 V, VDS = 0			±10	μA		
Gate threshold voltage	VTH	ID = 1.0 μA, VDS = 3.0 V	0.9	1.2	1.5	V		
Drain-source ON resistance	RDS(on)	ID = 10 mA, VGS = 2.5 V		8	15	Ω		
		ID = 10 mA, VGS = 4.0 V		6	12	Ω		
Forward transfer admittance	Yfs	ID = 10 mA, VDS = 3.0 V	20	60		mS		
Input capacitance	Ciss			12		pF		
Output capacitance	Coss	VDS = 3 V, VGS = 0, f = 1 MHz		7		pF		
Reverse transfer capacitance	Crss			3		pF		
Turn-on time <sup>*1</sup>	ton	VDD = 3 V, VGS = 0 to 3 V,		100		ns		
		ID = 10 mA		100				
Turn-off time <sup>*1</sup>	toff	VDD = 3 V, VGS = 3 to 0 V,		100		ns		
		ID = 10 mA				113		

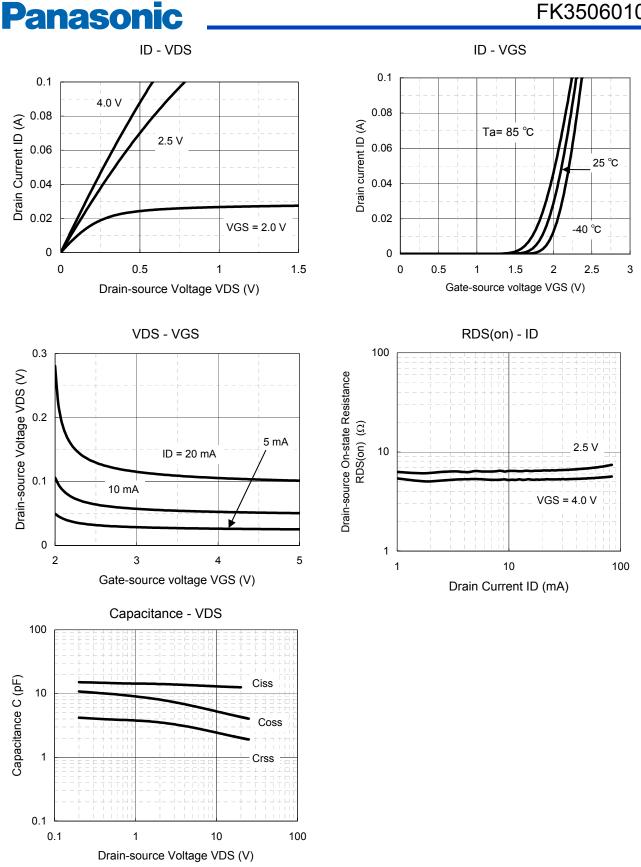
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.
2. \*1 Turn-on and Turn-off test circuit





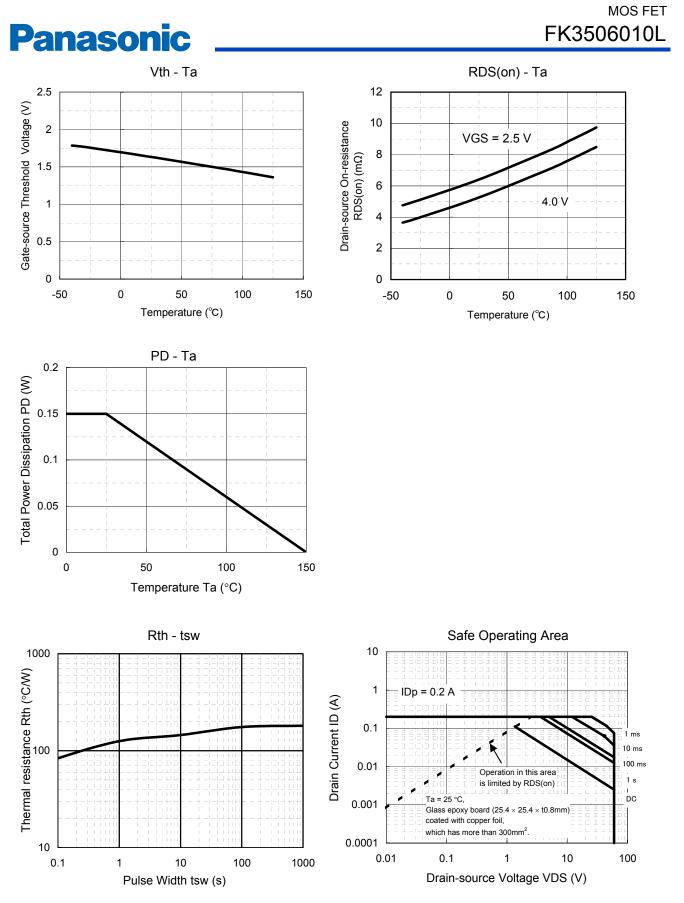


### MOS FET FK3506010L



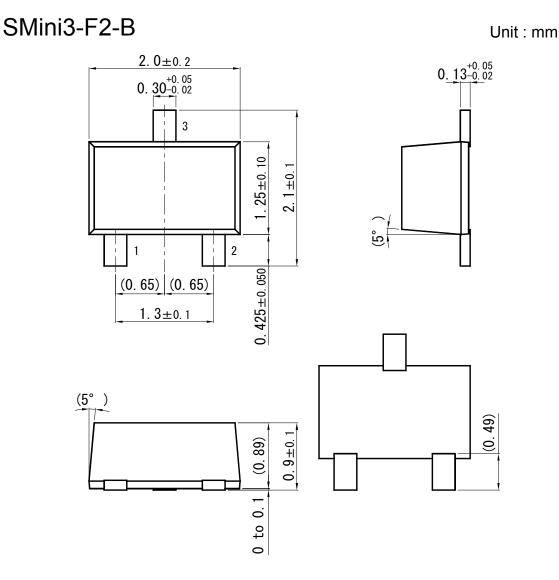
Established : 2010-06-07 Revised : 2013-07-08



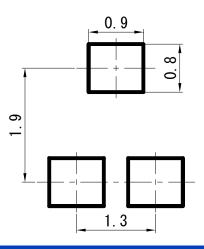




MOS FET FK3506010L



■ Land Pattern (Reference) (Unit : mm)



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Established : 2010-06-07 Revised : 2013-07-08

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